

Title (en)

Process to manufacture a thermal insulation compound system using an adhesive paste or filler

Title (de)

Verfahren zur Herstellung von Wärmedämmverbundsystemen mit Hilfe einer organischen Klebe- bzw. Spachtelmasse

Title (fr)

Procédé pour fabriquer un système composite pour isolation thermique en utilisant une pâte adhésive ou un mastic

Publication

**EP 1039058 B1 20041208 (DE)**

Application

**EP 00106349 A 20000323**

Priority

DE 19913315 A 19990324

Abstract (en)

[origin: EP1039058A1] The adhesive or filler is foamed prior to application to the insulation board and/or facade surface. The organic material is used as an adhesive to secure insulation boards to a building facade, as a filler to even out any facade surface irregularities prior to securing the insulation boards and/or to provide the mounted insulation boards with a reinforcing layer.

IPC 1-7

**E04B 1/76**; **E04F 13/08**

IPC 8 full level

**E04B 1/76** (2006.01); **E04F 13/08** (2006.01)

CPC (source: EP US)

**E04B 1/762** (2013.01 - EP US); **Y10T 428/249982** (2015.04 - EP US)

Citation (examination)

US 3765972 A 19731016 - WESP G

Cited by

EP2295671A1; DE102004035249B3; EP2607330A1; EP2196588A1; DE202008016581U1; WO2013042050A3; EP1974885A2; DE202005021508U1; EP1640521B2

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